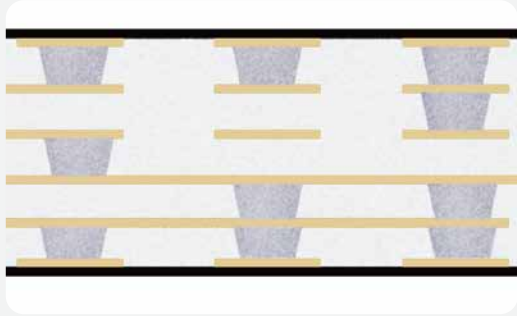


# Metallizing Paste

High reliability high layer count semiconductor package board application

## Applications

### Inter-layer connections



High layer count high-speed data transmission boards

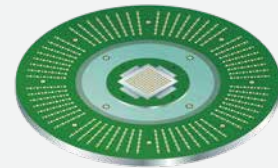
#### Consumer electronics

e.g. : High-speed data transmission substrates for smartphones



#### Automated test equipment (ATE) boards

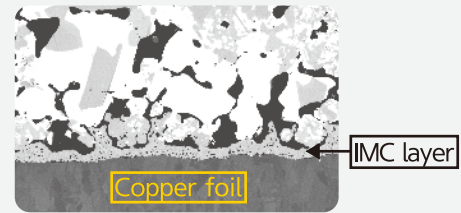
e.g. : Probe card



## Features

### What is "Metallizing paste"?

High and low melting point metal particles formulated, transient liquid phase sintering paste.  
High and low melting point metal particles formulate intermetallic compound (IMC) layers.  
IMC layers achieve high reliability connection on copper foil.



- IMC layer formation with copper foil. Stable circuit connection reliability with various base materials.
- High heat resistance and high thermal conductivity
- No through-hole plating required, enabling fine pitch routing

## Product line-up & properties

Product			MP8300	MPA500	MPA510	MPA550
Viscosity	BH type	dPa·s	1,400 - 2,200	1,000 - 2,000	900 - 1,700	1,200 - 2,000
Curing conditions			180°C × 60min.			
Volume resistivity (Representative value)		Ω·cm	8.0E-05	1.5E-04	2.0E-04	8.0E-05
Thermal conductivity (Laser flash method)		W/m·k	25	12		20
Glass-transition temperature/Tg		°C	151	147		

